

## Modifications for 28-layer stackup

Tom, after some reviewing of the old data I think we might be able to just have you make some adjustments which would allow us to be able to make a .128 thick, 28 layer, single lamination board.

Here is a matrix showing the parameters that were used and the adjusted sizes.

	Original size [mils]	Adjust to size [mils]
Via Size	5.91	10
	6.0	10
Thermal Size	19.9 x 27.9	23.5 x 40.5
Anti-pad Size	12.91	30
Signal pad Size	19.68	22
Impedance Trace Width	3.5	3

If you can make these adjustments then a single lamination should be possible.

*Sierra Circuits*